

REMARKS/ARGUMENTS

Favorable consideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1 and 90-121 are presently pending in this application, Claims 1 and 103 having been amended and Claims 116-121 having been added by the present amendment.

In the outstanding Office Action, Claims 1, 90-96, 100-110 and 113-115 were rejected under 35 U.S.C. §102(b) as being anticipated by Seyama et al. (U.S. Patent 5,586,006); Claims 97, 98, 111 and 112 were rejected under 35 U.S.C. §103(a) as being unpatentable over Seyama et al. in view of Ainslie et al. (U.S. Patent 4,418,857); and Claim 99 was rejected under 35 U.S.C. §103(a) as being unpatentable over Seyama et al. in view of JP 58-030175 (hereinafter “JP ‘175”).

First, Applicants acknowledges with appreciation the courtesy of telephone communication with Applicants’ representative on July 9, 2007. Pursuant to the discussion held during the telephone communication, Claims 1 and 103 have been amended to further clarify the bonding of the conductive connection pin. Specifically, Claim 1 has been amended to recite “a conductive connecting pin configured to establish an electrical connection with another substrate, the conductive connecting pin being secured to the partially exposed portion of the pad structure via a conductive adhesive agent, the conductive adhesive agent being disposed over at least one metal layer formed in the partially exposed portion of the pad structure,” and Claim 103 has been amended to recite “conductive connecting means for establishing an electrical connection with another substrate, the conductive connecting means being secured to the partially exposed portion of the pad structure via adhesive agent, the adhesive agent being disposed over at least one metal layer formed in the partially exposed portion of the pad structure.” In addition, new Claims 116-121 have been added herein. These amendments and additions in the claims find support in

the specification, claims and drawings as originally filed, for example, the specification, page 82, lines 15-29. Hence, no new matter is believed to be added thereby.

Seyama et al. is directed to a module having multi-layer circuit board with insulating layer and wiring conductors. Nevertheless, Seyama et al. does not teach or suggest “a conductive connecting pin configured to establish an electrical connection with another substrate, the conductive connecting pin being secured to the partially exposed portion of the pad structure via a conductive adhesive agent, *the conductive adhesive agent being disposed over at least one metal layer formed in the partially exposed portion of the pad structure*” as recited in amended Claim 1 (emphasis added in italic). Instead, Seyama et al. merely shows a conductive pin 34 attached to a pad 32 via solder. Thus, the structure recited in amended Claim 1 is clearly distinguishable over Seyama et al. and is not anticipated thereby.

Ainslie et al. and JP ‘175 are cited simply for “a pin made of Cu” and “constriction portion 601 having a diameter, which is smaller than the diameter of the outer portion,” and neither Ainslie et al. nor JP ‘175 teaches or suggests “a conductive connecting pin configured to establish an electrical connection with another substrate, the conductive connecting pin being secured to the partially exposed portion of the pad structure via a conductive adhesive agent, *the conductive adhesive agent being disposed over at least one metal layer formed in the partially exposed portion of the pad structure*” as recited in amended Claim 1 (emphasis added in italic). As such, the structure recited in amended Claim 1 is also distinguishable over Ainslie et al. and JP ‘175.

Since none of Seyama et al., Ainslie et al. and JP ‘175 discloses the conductive connecting pin structure as recited in amended Claim 1, even the combined teachings of these cited references would not render the structure recited in amended Claim 1 obvious.

As discussed above, Claim 103 has been amended to recite “conductive connecting means for establishing an electrical connection with another substrate, the conductive

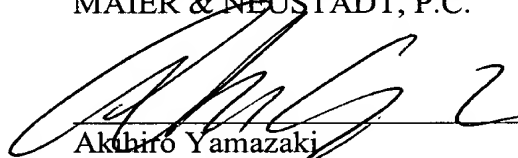
connecting means being secured to the partially exposed portion of the pad structure via adhesive agent, *the adhesive agent being disposed over at least one metal layer formed in the partially exposed portion of the pad structure*" (emphasis added in italics), and is therefore distinguishable over Seyama et al., Ainslie et al. and JP '175.

Based on the foregoing discussions, Claims 1 and 103 are believed to be allowable. Furthermore, Claims 90-102 and 104-121 depend either Claim 1 or 103 and thus substantially the same reasons set forth above for Claims 1 and 103 are also applicable to these dependent claims. Thus, Claims 90-102 and 104-121 are believed to be allowable as well.

In light of the discussions during the telephone communication and in view of the amendments presented above, the present application is believed to be in condition for allowance. If, however, the Examiner disagrees with any of the amendments presented above, the Examiner is invited to telephone the undersigned who will be happy to work in a joint effort to derive mutually satisfactory claim language and expedite the prosecution of the present application. Applicants respectfully request an early and favorable action to the effect discussed above.

Respectfully submitted,

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